

WHAT IS CLAIMED IS:

1. An article of manufacture comprising:
 - a metal layer;
 - a first dielectric layer in contact with a first face of the metal layer; and
 - 5 a second dielectric layer in contact with a second face of the metal layer, the second face being opposite to the first face;

wherein the metal layer is a substantially continuous sheet having slots formed therein to allow the first and second dielectric layers to adhere to each other by way of the slots.
- 10 2. The article of claim 1, wherein each of the slots has a length:width ratio of at least 5:1.
3. The article of claim 2, wherein the length:width ratio of each slot is at least 10:1.
4. The article of claim 1, wherein the slots are arrayed substantially in a rectangular pattern.
- 15 5. The article of claim 4, wherein the slots are arrayed substantially in a face-centered rectangular pattern.
6. The article of claim 5, wherein rectangular cells of the pattern have an aspect ratio of substantially 1.73:1.

7. The article of claim 1, wherein a first one of the slots has an orientation that is at an angle relative to an orientation of a second one of the slots.
8. The article of claim 1, wherein each of the slots has a width dimension of substantially 50 microns.
- 5 9. The article of claim 1, wherein the metal layer operates as a ground plane.
10. The article of claim 1, wherein the metal layer operates as a power plane.
11. A method comprising:
- forming a metal layer on a first dielectric layer; and
- forming a second dielectric layer on the metal layer;
- 10 the metal layer being patterned as a substantially continuous sheet having slots formed therein to allow the first and second dielectric layers to adhere to each other by way of the slots.
12. The method of claim 11, wherein each of the slots has a length:width ratio of at least 5:1.
- 15 13. The method of claim 12, wherein the length:width ratio of each slot is at least 10:1.
14. The method of claim 11, wherein the slots are arrayed substantially in a face-centered rectangular pattern.

15. The method of claim 14, wherein rectangular cells of the pattern have an aspect ratio of substantially 1.73:1.
16. The method of claim 11, wherein a first one of the slots has an orientation that is at an angle relative to an orientation of a second one of the slots.
- 5 17. The method of claim 11, wherein each of the slots has a width dimension of substantially 50 microns.
18. A system comprising:
- a substrate;
 - a die mounted on the substrate and comprising an integrated circuit; and
 - 10 a chipset in communication with the integrated circuit via the substrate;
- wherein the substrate comprises:
- a metal layer;
 - a first dielectric layer in contact with a first face of the metal layer; and
 - a second dielectric layer in contact with a second face of the metal layer,
- 15 the second face being opposite to the first face;
- wherein the metal layer is a substantially continuous sheet having slots formed therein to allow the first and second dielectric layers to adhere to each other by way of the slots.

19. The system of claim 18, wherein each of the slots has a length:width ratio of at least 5:1.
20. The system of claim 19, wherein the length:width ratio of each slot is at least 10:1.
21. The system of claim 18, wherein the slots are arrayed substantially in a rectangular pattern.
- 5
22. The system of claim 21, wherein the slots are arrayed substantially in a face-centered rectangular pattern.
23. The system of claim 22, wherein rectangular cells of the pattern have an aspect ratio of substantially 1.73:1.
- 10
24. The system of claim 18, wherein a first one of the slots has an orientation that is at an angle relative to an orientation of a second one of the slots.
25. The system of claim 18, wherein each of the slots has a width dimension of substantially 50 microns.
26. The system of claim 18, wherein the metal layer operates as a ground plane.
- 15
27. The system of claim 18, wherein the metal layer operates as a power plane.